

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
Contact Info: ti.com/support  
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
Created on: 06/04/2022

Details for "OPA207IDBVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
OPA207IDBVR	NIPDAUAG	Level-2-260C-1 YEAR	Ext-Mfg	DBV   5	2.9x1.6x1.45	18.4

\*Total Device Mass  
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Not Categorized	Proprietary Materials		0.000002	0.005688	57	0.000011	0
Precious Metals	Gold	7440-57-5	0.035161	99.994312	999943	0.191256	1913
Sub-Total			0.035163	100	1000000	0.191267	1913
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.03163	29.99981	299998	0.172049	1720
Other Inorganic Materials	Silica	7631-86-9	0.004745	4.500446	45004	0.02581	258
Other Organic Materials	Chlorine	7782-50-5	0.000037	0.035093	351	0.000201	2
Thermoplastics	Epoxy	85954-11-6	0.069022	65.464651	654647	0.37544	3754
Sub-Total			0.105434	100	1000000	0.573501	5735
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	5.53185	97.05	970500	30.090108	300901
Copper and Its Alloys	Iron	7439-89-6	0.1482	2.6	26000	0.806123	8061
Copper and Its Alloys	Phosphorus	7723-14-0	0.00855	0.15	1500	0.046507	465
Zinc and Its Alloys	Zinc	7440-66-6	0.0114	0.2	2000	0.062009	620
Sub-Total			5.7	100	1000000	31.004748	310047
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.1946	97.3	973000	1.058513	10585
Precious Metals	Gold	7440-57-5	0.0006	0.3	3000	0.003264	33
Precious Metals	Palladium	7440-05-3	0.0042	2.1	21000	0.022846	228
Precious Metals	Silver	7440-22-4	0.0006	0.3	3000	0.003264	33
Sub-Total			0.2	100	1000000	1.087886	10879
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	9.911712	84.999997	850000	53.914058	539141
Other Plastics and Rubber	Carbon Black	1333-86-4	0.034983	0.300004	3000	0.190288	1903
Thermoplastics	Epoxy	85954-11-6	1.714143	14.699998	147000	9.32396	93240
Sub-Total			11.660838	100	1000000	63.428306	634283
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.682846	100	1000000	3.714293	37143
Sub-Total			0.682846	100	1000000	3.714293	37143
Total			18.384281			100	1000000

**Important Note**  
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**  
TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**  
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[For additional information, please contact TI customer support.](#)  
  
[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.